



Power MOSFETS

DATASHEET

LM30048NAI8A

N-Channel
Enhancement Mode MOSFET

 Leadpower-semiconductor Corp., Ltd

 sales@leadpower-semi.com

 (03) 6577339 FAX : (03) 6577229

 www.leadpower-semi.com

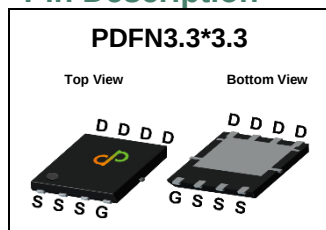


Quality Management Systems

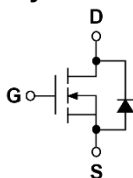
ISO 9001:2015 Certificate

N-Channel Enhancement Mode MOSFET

Pin Description



Symbol



Product Summary

Symbol	N-Channel	Unit
V_{DS}	30	V
$R_{DS(ON)-Max}$	4.8	mΩ
ID	64	A

Feature

- Lower $R_{DS(ON)}$ to Minimize Conduction Losses
- Reliable and Rugged
- ROHS Compliant & Halogen-Free
- 100% UIS and Rg Tested

Applications

- Portable Equipment and Battery Powered systems.
- Power Management in Notebook Computer

Ordering Information

Orderable Part Number	Package Type	Form	Shipping	Marking
LM30048NAI8A	PDFN3.3*3.3	Tape & Reel	5000 / Tape & Reel	30048 □□□□□□

Note : □□□□□□ = Lot Code

Absolute Maximum Ratings ($T_J=25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	N-Channel	Unit
V_{DS}	Drain-Source Voltage	30	V
V_{GS}	Gate-Source Voltage	± 20	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
$I_{DM}^{①}$	Pulse Drain Current Tested	$T_c=25^\circ\text{C}$	A
I_D	Continuous Drain Current	$T_c=25^\circ\text{C}$	A
		$T_c=100^\circ\text{C}$	
P_D	Maximum Power Dissipation	$T_c=25^\circ\text{C}$	W
		$T_c=100^\circ\text{C}$	
$I_{AS}^{②}$	Avalanche Current, Single pulse	$L=0.1\text{mH}$	A
$E_{AS}^{②}$	Avalanche Energy, Single pulse	$L=0.1\text{mH}$	mJ

Thermal Characteristics

Symbol	Parameter	Rating	Unit
$R_{\theta JC}$	Thermal Resistance-Junction to Case	Steady State	$^\circ\text{C/W}$
$R_{\theta JA}^{③}$	Thermal Resistance-Junction to Ambient	Steady State	$^\circ\text{C/W}$

Note ① : Max. current is limited by bonding wire

Note ② : UIS tested and pulse width are limited by maximum junction temperature 150°C

Note ③ : Surface Mounted on 1in^2 FR-4 board with 1oz.

N-Channel Electrical Characteristics ($T_J=25^{\circ}\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Electrical Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _{DS} =250uA	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =24V, V _{GS} =0V	-	-	1	uA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _{DS} =250uA	1.1	1.6	2.1	V
I _{GSS}	Gate Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
R _{DS(ON)} ④	Drain-Source On-state Resistance	V _{GS} =10V, I _{DS} =20A	-	4.1	4.8	mΩ
		V _{GS} =4.5V, I _{DS} =18A	-	5.3	6.9	
gfs	Forward Transconductance	V _{DS} =5V, I _{DS} =20A	-	22	-	S
Dynamic Characteristics ⑥						
R _G	Gate Resistance	V _{GS} =0V, V _{DS} =0V, Freq.=1MHz	-	2.2	-	Ω
C _{iss}	Input Capacitance	V _{GS} =0V, V _{DS} =15V, Freq.=1MHz	-	1859	-	pF
C _{oss}	Output Capacitance		-	260	-	
C _{rss}	Reverse Transfer Capacitance		-	212	-	
td(ON)	Turn-on Delay Time	V _{GS} =10V, V _{DS} =15V, I _D =1A, R _{GEN} =6Ω	-	9.6	-	nS
t _r	Turn-on Rise Time		-	23.4	-	
t _{d(OFF)}	Turn-off Delay Time		-	62.8	-	
t _f	Turn-off Fall Time		-	23	-	
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =25V I _D =14A	-	26	-	nC
Q _g	Total Gate Charge	V _{GS} =10V, V _{DS} =25V, I _D =14A	-	48	-	
Q _{gs}	Gate-Source Charge		-	3.4	-	
Q _{gd}	Gate-Drain Charge		-	14	-	
Source-Drain Characteristics						
V _{SD} ④	Diode Forward Voltage	I _{SD} =1A, V _{GS} =0V	-	0.75	1.1	V
t _{rr}	Reverse Recovery Time	I _F =2A, V _R =0V	-	18.2	-	nS
Q _{rr}	Reverse Recovery Charge	dI _F /dt=100A/μs	-	9.2	-	nC

Note ④ : Pulse test (pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$).

Note ⑤ : Guaranteed by design, not subject to production testing.

N-Channel Typical Characteristics

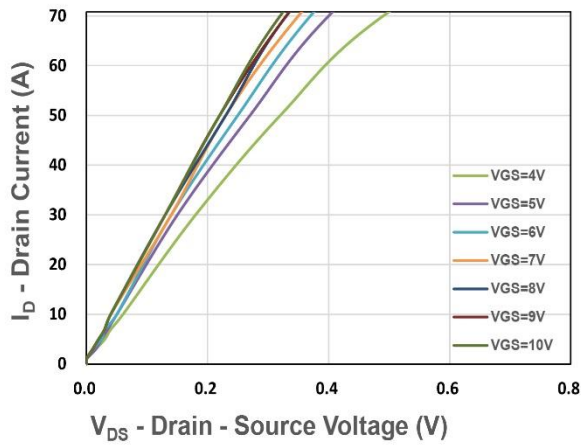


Figure 1. Output Characteristics

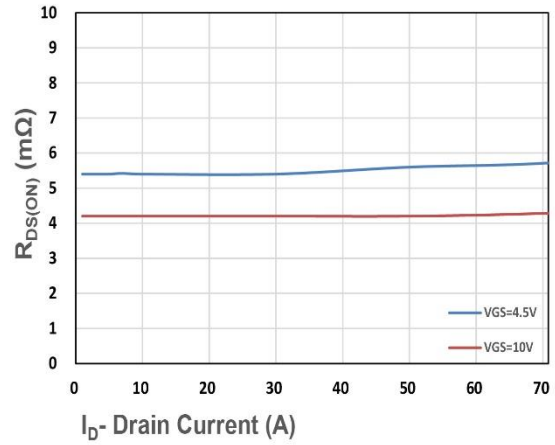


Figure 2. On-Resistance vs. I_D

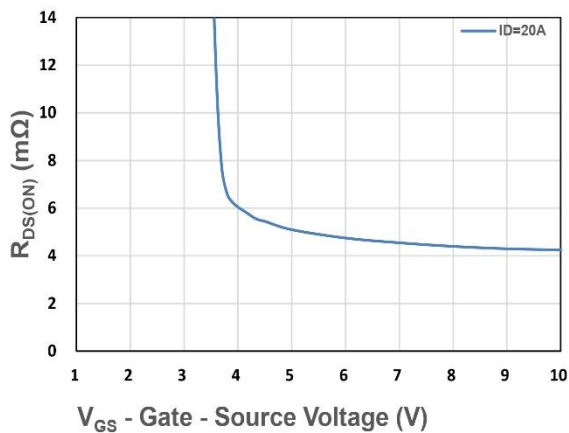


Figure 3. On-Resistance vs. V_{GS}

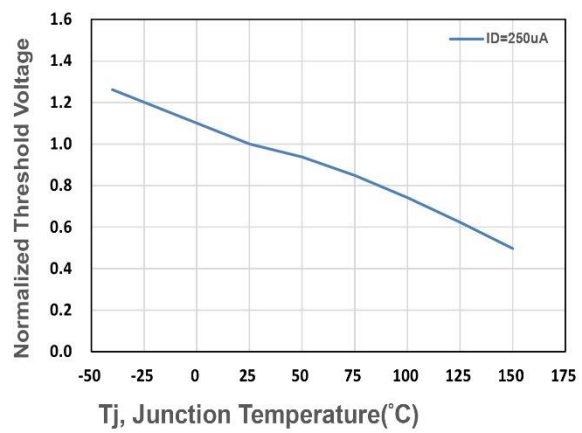


Figure 4. Gate Threshold Voltage

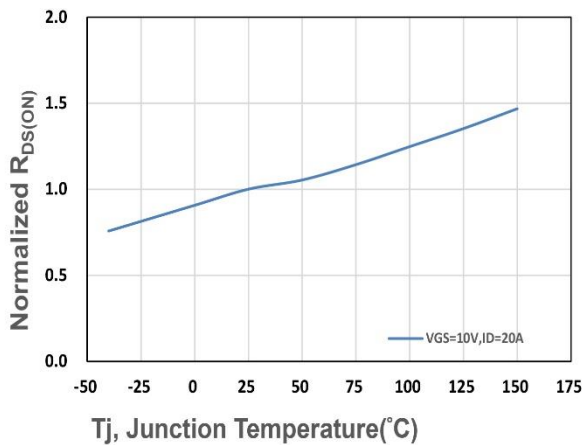


Figure 5. Drain-Source On Resistance

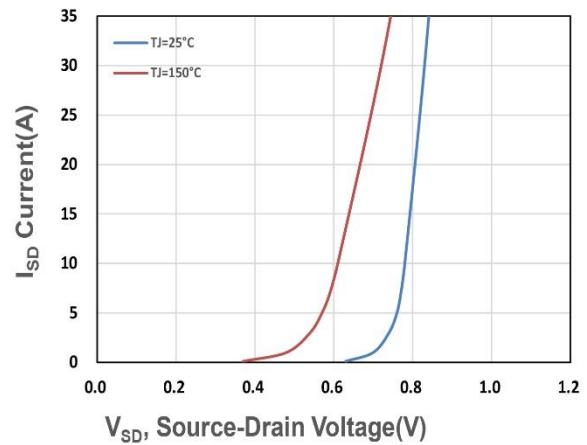


Figure 6. Source-Drain Diode Forward

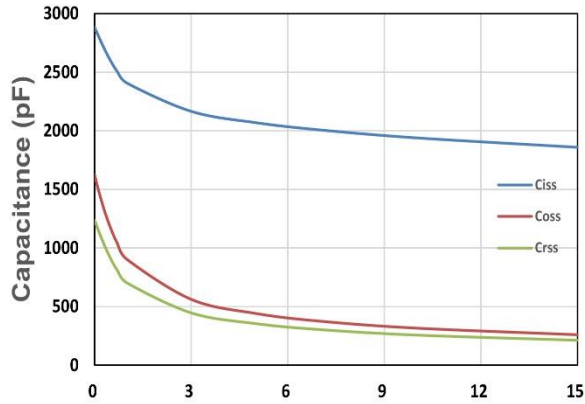


Figure 7. Capacitance

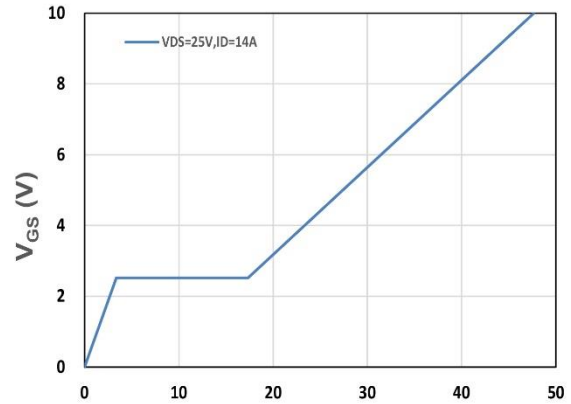


Figure 8. Gate Charge Characteristics

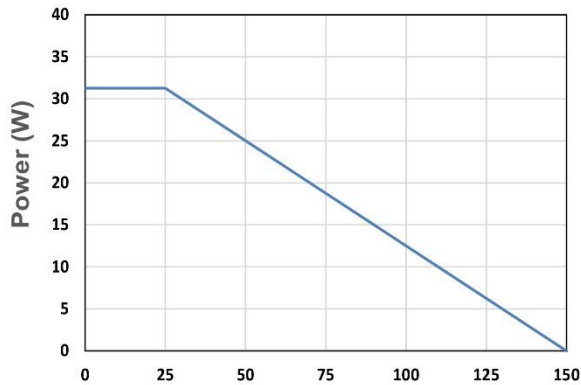


Figure 9. Power Dissipation

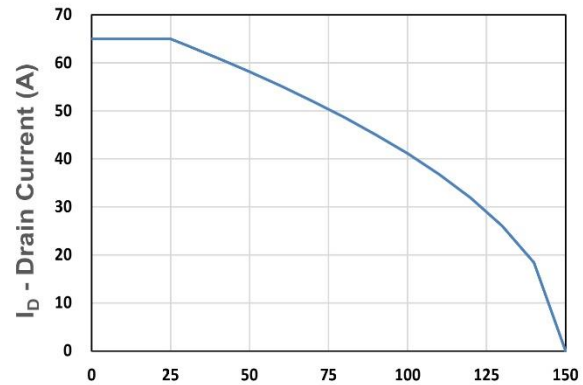


Figure 10. Drain Current

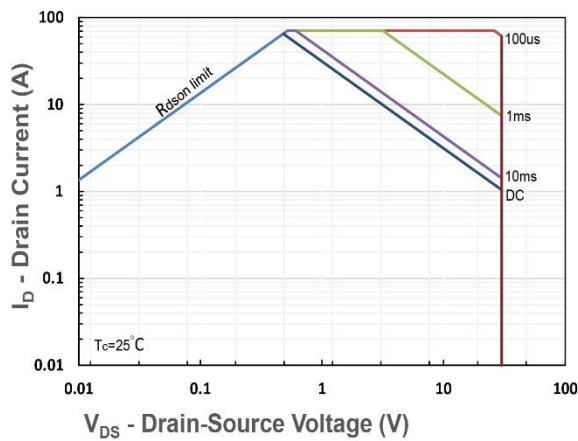


Figure 11. Safe Operating Area

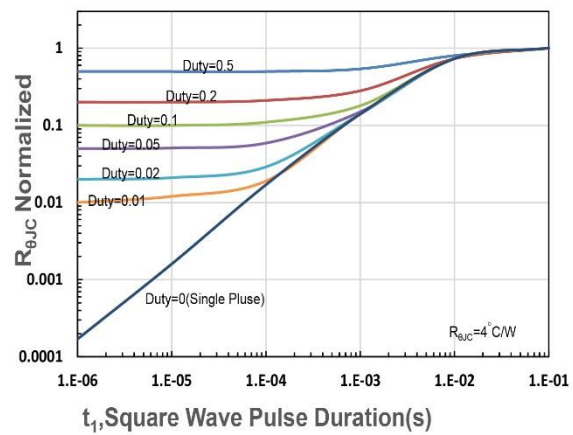


Figure 12. $R_{\theta JC}$ Transient Thermal Impedance